

Electronic Patent Application Fee Transmittal

Application Number:	10595424			
Filing Date:	18-Apr-2006			
Title of Invention:	Semiconductor chip mounted interposer, semiconductor device, semiconductor chip interposer fabrication method, bare chip mounted interposer, and interposer sheet			
First Named Inventor/Applicant Name:	Moriyoshi Nakashima			
Filer:	Mark D. Saralino/Christine Arndt			
Attorney Docket Number:	KOMOP0113US			

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Extension - 1 month with \$0 paid	1251	1	120	120
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120